

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P _{PP}	90	W	8/20μs, Per Figure 2
Peak Pulse Current	I _{PP}	3	A	8/20μs, Per Figure 2
ESD Protection – Contact Discharge	V _{ESD Contact}	±30	kV	Standard IEC 61000-4-2
ESD Protection – Air Discharge	V _{ESD Air}	±30	kV	Standard IEC 61000-4-2

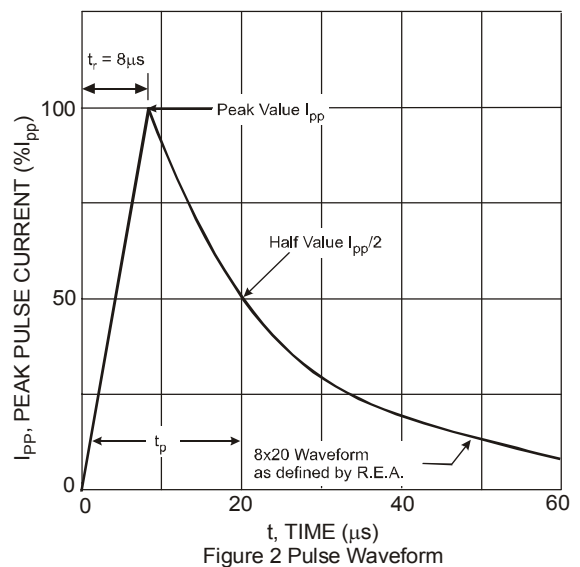
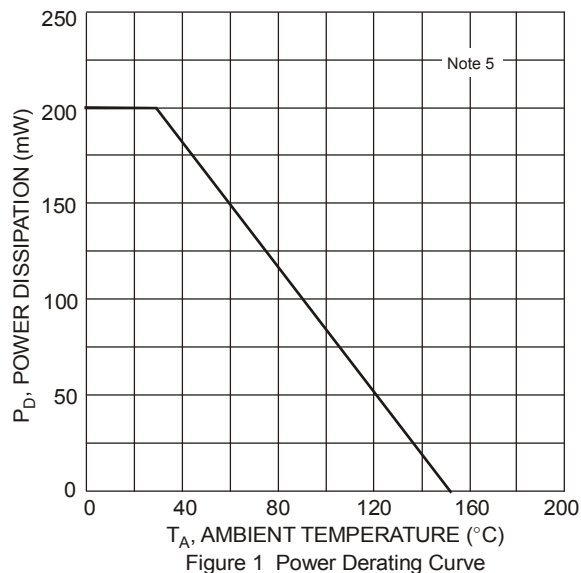
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P _D	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	R _{θJA}	625	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Standoff Voltage	V _{RWM}	—	—	20	V	—
Channel Leakage Current (Note 6)	I _{RM}	—	—	100	nA	V _{RWM} = 20V
Clamping Voltage, Positive Transients	V _{CL}	—	—	27	V	I _{PP} = 1A, t _p = 8/20μs
		—	—	30	V	I _{PP} = 3A, t _p = 8/20μs
Breakdown Voltage	V _{BR}	21	—	25	V	I _R = 1mA
Differential Resistance	R _{DIF}	—	1.8	—	Ω	I _R = 1A, t _p = 8/20μs
Channel Input Capacitance	C _T	—	10	15	pF	V _R = 0V, f = 1MHz

- Notes:
- Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.
 - Short duration pulse test used to minimize self-heating effect.



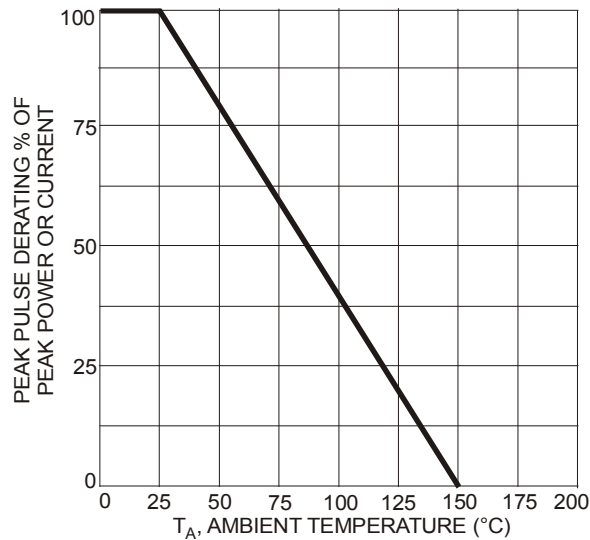


Figure 3 Power Dissipation vs. Ambient Temperature

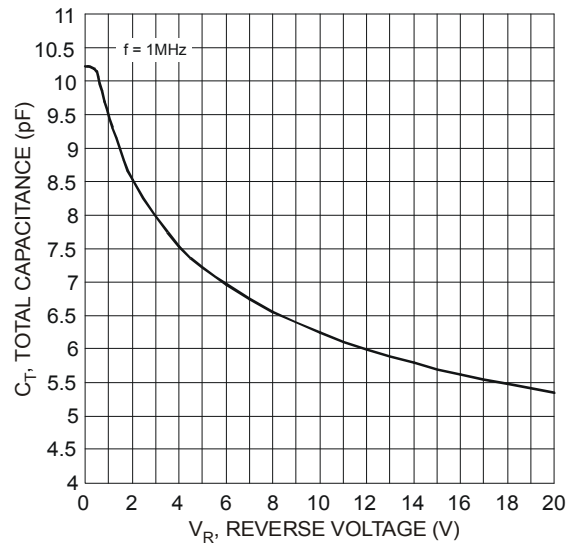


Figure 4 Typical Total Capacitance vs. Reverse Voltage

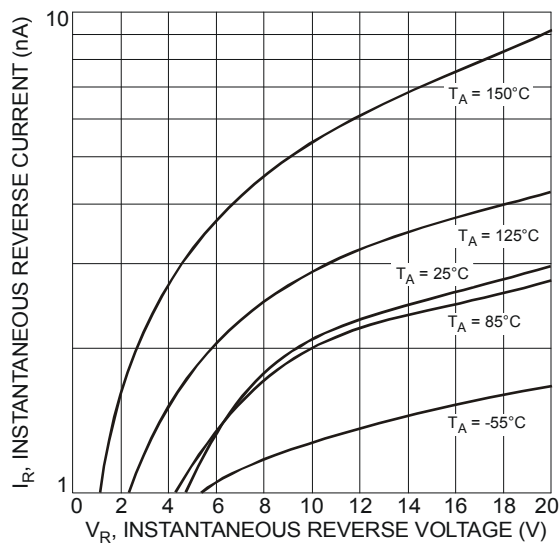
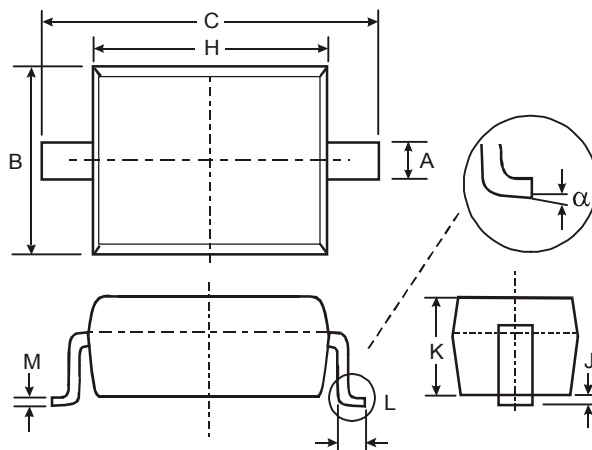


Figure 5 Typical Reverse Characteristics

Package Outline Dimensions

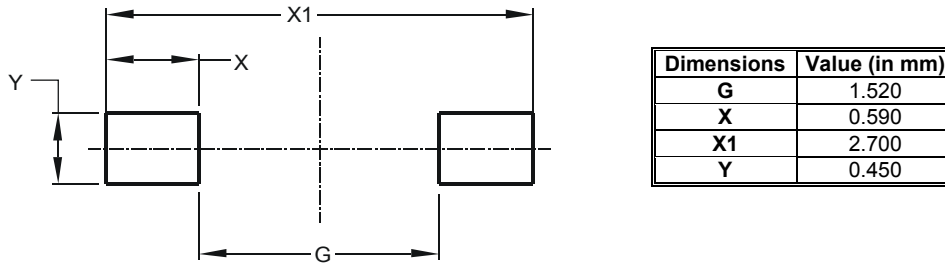
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOD323		
Dim	Min	Max
A	0.25	0.35
B	1.20	1.40
C	2.30	2.70
H	1.60	1.80
J	0.00	0.10
K	1.0	1.1
L	0.20	0.40
M	0.10	0.15
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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